

Title (en)  
METHOD OF SEALING A RELAY

Publication  
**EP 0118841 A3 19850123 (DE)**

Application  
**EP 84102158 A 19840301**

Priority  
DE 3308791 A 19830312

Abstract (en)  
[origin: ES8504406A1] A relay is sealed with a sealing compound when the relay housing is in a closed state, thus causing an air cushion to be formed in the inside, with an afterflow of sealing compound into the interior being prevented. Following gelling or curing of the sealing compound, a vent hole is pierced into the relay housing which, if required, may be closed following degassing of the interior space of the relay.

IPC 1-7  
**H01H 50/02**

IPC 8 full level  
**H01H 49/00** (2006.01); **H01H 50/02** (2006.01)

CPC (source: EP US)  
**H01H 50/023** (2013.01 - EP US); **Y10T 29/49002** (2015.01 - EP US); **Y10T 29/4902** (2015.01 - EP US)

Citation (search report)

- [Y] DE 2732517 A1 19780629 - ZETTLER ELEKTROTECHN ALOIS
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Designated contracting state (EPC)  
AT BE FR GB

DOCDB simple family (publication)  
**EP 0118841 A2 19840919; EP 0118841 A3 19850123; EP 0118841 B1 19880120**; AT E32151 T1 19880215; CA 1234462 A 19880329; DE 3308791 A1 19840920; DE 3308791 C2 19860821; ES 530501 A0 19850401; ES 8504406 A1 19850401; JP H0572049 B2 19931008; JP S59175528 A 19841004; US 4675987 A 19870630

DOCDB simple family (application)  
**EP 84102158 A 19840301**; AT 84102158 T 19840301; CA 448710 A 19840302; DE 3308791 A 19830312; ES 530501 A 19840312; JP 4534584 A 19840309; US 58710884 A 19840307